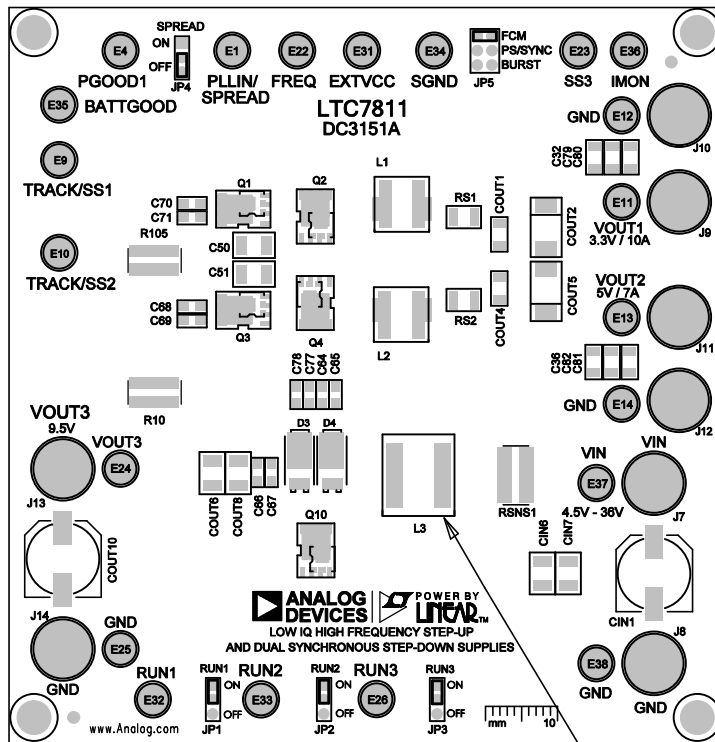


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	LJ	11-18-20

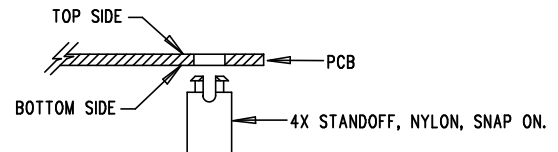


ANALOG DEVICES
DC3151A-2 11-18-20

TOP SILKSCREEN
TOP ASSEMBLY

NOTES: UNLESS OTHERWISE SPECIFIED



1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AS SHOWN BELOW:



INSTALL L1, L2 AND L3 WITH THE LINE
MARKING CLOSED TO MOSFETS SIDE



DETAIL A

APPROVALS		 ANALOG DEVICES		 POWER BY LINEAR™		www.Analog.com FOR ADI CUSTOMER USE ONLY	
PCB DES.	LT	TITLE: TOP ASSEMBLY DRAWING LOW IQ HIGH FREQUENCY STEP-UP AND DUAL SYNCHRONOUS STEP-DOWN SUPPLIES					
APP ENG.	LJ						
		SIZE N/A	IC NO. LTC7811EUJ DC3151A	REV. 2			
SCALE = NONE		FILENAME: DC3151A-2.PCB				SHT 1 OF 2	